

• General Description

The AGM55P10D combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

This device is ideal for load switch and battery protection applications.

Features

- Advance high cell density Trench technology
- Low R_{DS(ON)} to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% Avalanche tested
- 100% DVDS tested

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

Product Summary

BVDSS	RDSON	ID
-100V	52mΩ	-30A

TO-252 Pin Configuration



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
AGM55P10D	AGM55P10D	TO-252	330mm	16mm	2500

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	-100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
lD	Drain Current-Continuous(Tc=25°C) (Note 1)	-30	А
	Drain Current-Continuous(Tc=100℃)	-18	А
IDM (pluse)	Drain Current-Pulsed (Note 2)	-120	Α
	Maximum Power Dissipation(Tc=25℃)	50	W
PD	Maximum Power Dissipation(Tc=100℃)	20	w
EAS	Avalanche energy (Note 3)	196	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	${\mathbb C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State) ¹		50	°C/W
RøJC	Thermal Resistance Junction-Case ¹		2.5	°C/W



Table 3. Electrical Characteristics (TJ=25℃ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
On/Off Sta	ites						
BVDSS	Drain-Source Breakdown Voltage	VGS=0V ID=-250μA	-100			V	
IDSS	Zero Gate Voltage Drain Current	VDS=-100V,VGS=0V			-1	μΑ	
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V			±100	nA	
VGS(th)	Gate Threshold Voltage	VDS=VGS,ID=-250μA	-1.2	-1.6	-2.2	V	
gFS	Forward Transconductance	VDS=-5V,ID=-5A		18		S	
RDS(on)	Drain-Source On-State Resistance	VGS=-10V, ID=-10A		52	71	mΩ	
1.20(01.)		VGS=-4.5V, ID=-5A		63	77	mΩ	
Dynamic 0	Characteristics						
Ciss	Input Capacitance	VD0 4044400 04		3500		pF	
Coss	Output Capacitance	VDS=-40V,VGS=0V ,F=1MHZ		106		pF	
Crss	Reverse Transfer Capacitance			90		pF	
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz		2.2		Ω	
Switching	Times						
td(on)	Turn-on Delay Time			49		nS	
tr	Turn-on Rise Time	VGS=-10V,VDS=-50V,		71		nS	
td(off)	Turn-Off Delay Time	ID=-10A,RGEN=4.5Ω		555		nS	
tf	Turn-Off Fall Time			187		nS	
Qg	Total Gate Charge			773		nC	
Qgs	Gate-Source Charge	VGS=-10V, VDS=-50V, ID=-10A		17		nC	
Qgd	Gate-Drain Charge			9.1		nC	
Source-Drain Diode Characteristics							
ISD	Source-Drain Current(Body Diode)				-30	Α	
VSD	Forward on Voltage	VGS=0V,IS=-10A			-1.2	V	
trr	Reverse Recovery Time	Isd=-10A ,		32		ns	
Qrr	Reverse Recovery Charge	dl/dt=100A/µs , TJ=25℃		49		nc	

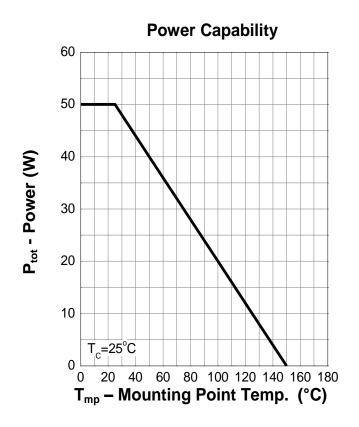
Notes 1.The maximum current rating is package limited.

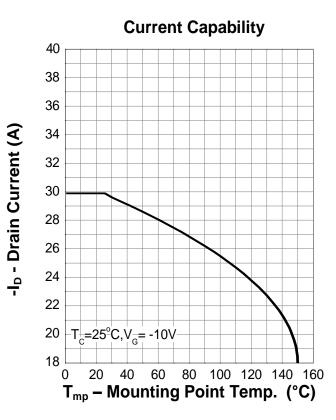
Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

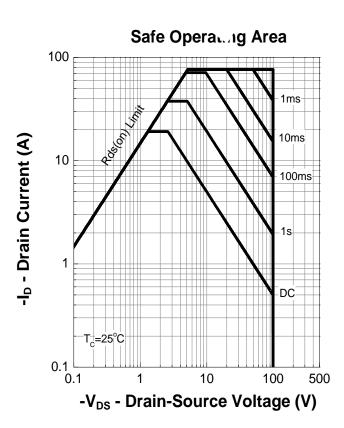
Notes 3.EAS condition: TJ=25 $^{\circ}$ C,VDD=-50V,Vgs=-10V,ID=-28A, L=0.5mH,RG=25ohm

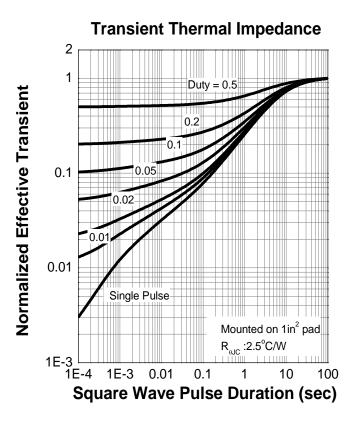


Typical Characteristics



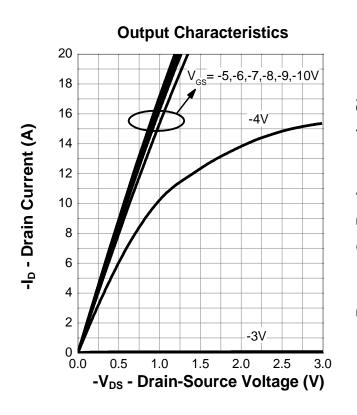


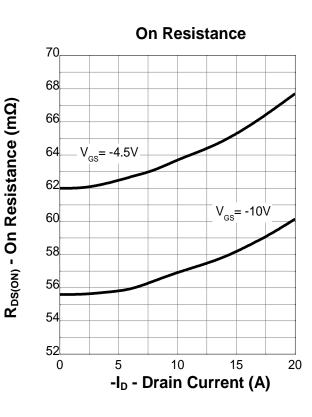


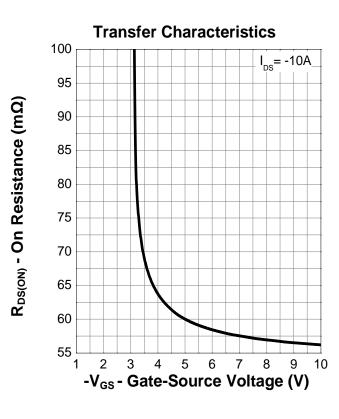


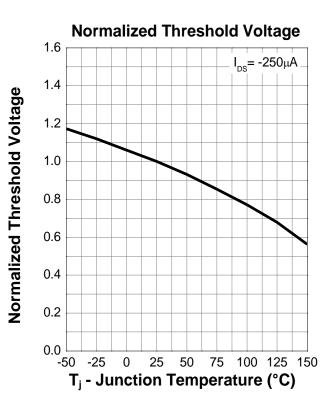


Typical Characteristics (cont.)



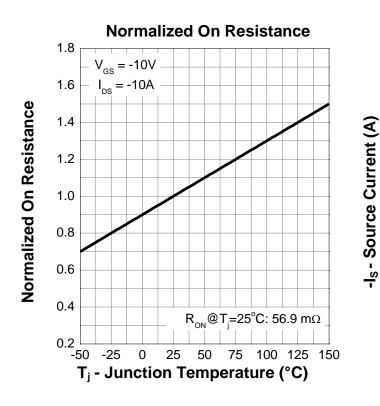


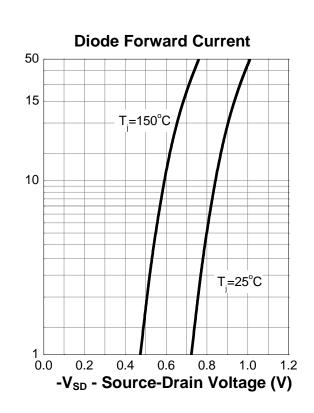


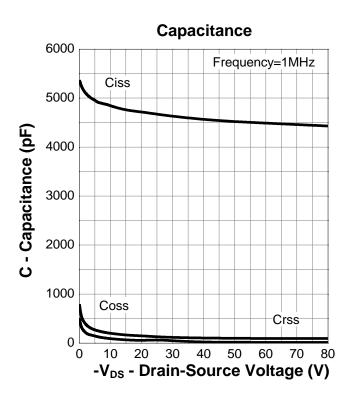


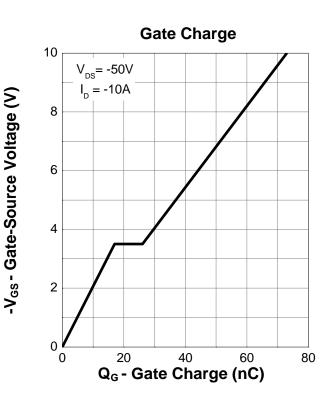


Typical Characteristics (cont.)



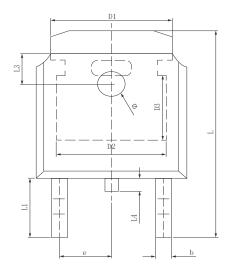


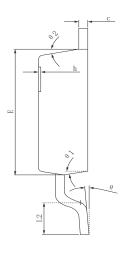


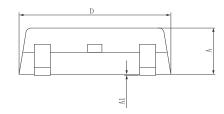


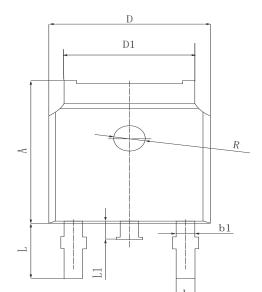


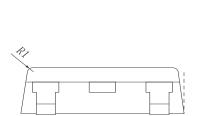
•Dimensions (TO-252)

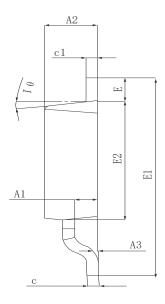


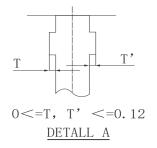






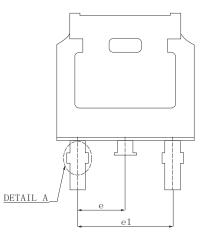






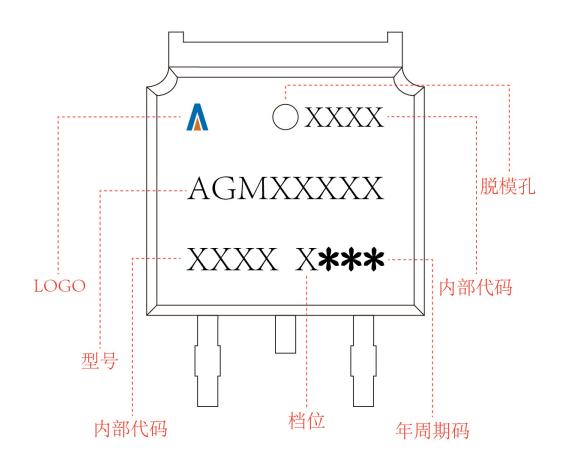
	MILLIMETER				
SYMBOL	MIN	Typ.	MAX		
A	2.200	2. 300	2.400		
A1	0.000		0. 127		
b	0.640	0.690	0.740		
c(电镀后)	0.460	0.520	0.580		
D	6.500	6.600	6. 700		
D1	5. 334 REF				
D2	4.826 REF				
D3	3.166 REF				
Е	6.000	6.100	6. 200		
е		2.286 TYP			
h	0.000	0.100	0.200		
L	9.900	10.100	10.300		
L1		2.888 REF			
L2	1.400	1.550	1.700		
L3	1.600 REF				
L4	0.600	0.800	1.000		
Φ	1.100	1. 200	1.300		
θ	0°		8°		
θ 1	9° TYP				
θ2	9° TYP				

SYMBOL	MILLIMETER			
	MIN	NOM	MAX	
A	7.050	7. 100	7. 150	
A1	0.960	1.010	1.060	
A2	2. 250	2.300	2.350	
A3	0.000	0.050	0.100	
b	0.760REF.			
b1	1.000REF.			
С	0. 508REF.			
c1	0. 508REF.			
D	6. 550	6.600	6.650	
D1	5. 220	5. 320	5. 420	
Е	0.950	1.000	1.050	
E1	9.700	9.900	10.100	
E2	6.050	6. 100	6.150	
е	2. 286BSC			
e1	4. 572REF.			
L	2.650	2.800	2.950	
L1	0.700 0.800 0.900			
θ 1	7° REF.			
R	1.300REF.			
R1	0.250REF.			





TO-252 Marking Instructions:





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